Ms. Susanna Kooistra
Mr. Issam Toufik
3GPP Mobile Competence Center
c/o ETSI
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06921 Sophia Antipolis Cedex
France

Nomination of candidate for 3GPP TSG RAN WG3 Vice Chairman

Dear Susanna and Issam,

Ericsson is delighted to announce the nomination of Dr. Angelo Centonza as candidate for a second term of the Vice Chairmanship of 3GPP TSG RAN WG3. Angelo is representing Ericsson LM, a member of ETSI.

Angelo graduated in 2002 from Politecnico di Bari with a Master of Science degree in Electrical Engineering, and he also holds a PhD on Hybrid Telecommunication Networks from Brunel University, London. He has been with Ericsson since 2011 after having worked in several technical and business-oriented roles at Huawei, Nokia, Siemens and after having spent a period of time as research assistant at Brunel University. Angelo's broad experience ranges from telecommunication networks for defense systems to system automation and architectures for 3G, 4G and 5G.

Angelo started his journey with telecom standards in 2007 with IEEE 802.11. He has been participating in 3GPP RAN3 since 2008, contributing over a wide range of topics for UMTS, LTE and NR, and chairing sessions on topics such as Home NodeBs, Relays and SON.

As TSG RAN WG3 Vice Chairman candidate, Angelo has been trained to comply with all applicable antitrust/competition laws and regulations.

Ericsson is fully committed to supporting Angelo in his tasks as Vice Chairman of 3GPP TSG RAN WG3.

Stockholm, May 3, 2023

Per Beming
VP Head of Standards & Industry Initiatives

Angelo Centonza – RAN3 Vice Chair Candidate

- Ericsson in 3GPP and RAN3
  - A leading company in 3GPP and in the entire ecosystem
  - Active in all TSGs, all WGs, all topics
  - Committed to taking responsibility and driving 5G in 3GPP and in RAN3

- Angelo Centonza
  - MSEE (Politecnico di Bari); PhD (Brunel University, London)
  - Previous work at Brunel University, Siemens, Nokia-Siemens, Huawei, Ericsson
  - Broad Knowledge
    - RAN Architectures, 3G/4G/5G systems and protocols, automation, virtualisation, cloud systems
  - In standardisation since 2007: IEEE 802.11, IETF, 3GPP
  - Active in 3GPP RAN3 since 2008:
    - 5G/4G Split Architectures, SON, AI/ML, Network Slicing, Relays, HetNet, NB IoT, Home NBs/eNBs, MBMS,
  - Rapporteur for RAN3 «Enhancement of Data Collection for SON/MDT in NR" WI
  - Chairing Experience: RAN3 Vice Chairman since May 2021 to date